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Product Change Notification - JAON-29UXDQ760   (Printer Friendly)

Date:	08 Jan 2016
Notification subject:	CCB 1751 and 1751.01 Final Notice: Qualification of CuPdAu bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.
Notification text:	**PCN Status:**

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

Pre Change:
Gold (Au) or Palladium coated copper wire (PdCu) bond wire

Post Change:
Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI assembly site
Wire material	Au wire or PdCu wire	Au wire or CuPdAu wire
Die attach material	3280	3280
Molding compound material	SG-8300ECM[a] or G700HA	SG-8300ECM[a] or G700HA
Lead frame material	C7025	C7025

Note: [a] SG-8300ECM mold compound can only be used with Au wire. It cannot be used with either of the PdCu wire or CuPdAu wire options

Impacts to Data Sheet:
None

Reason for Change:
To improve on-time delivery performance by qualifying Palladium coated copper with gold flash (CuPdAu) bond wire

Change Implementation Status:
In Progress

Estimated First Ship Date:
January 22, 2016 (date code: 1603)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

		October 2015				November 2015				December 2015					January 2016			
	WW	41	42	43	44	45	46	47	48	49	50	51	52	53	01	02	03	04
Initial PCN Issue Date			X															
Qual Report Availability									X									
Final PCN Issue Date															X			
Implementation Date																	X	

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
October 14, 2015: Issued initial notification.
January 8, 2016: Issued final notification. Attached the qualification report. Revised the estimated first ship date from November 30, 2015 to January 22, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):   PCN_JAON-29UXDQ760_Qual_Report.pdf
PCN_JAON-29UXDQ760_Affected_CPN.pdf
PCN_JAON-29UXDQ760_Affected_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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